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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10021708	FILING DATE 12/19/2001	CLASS 217 A32	SUBCLASS 390	GAU 3742 3749	EXAMINER Fujita
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**APPLICANTS: Yamazaki Shunpei;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 2000-403268 12/28/2000

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed

☒ yes ☐ no

35 USC 119 conditions met

☒ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

740756-2412

TITLE : Heat treatment apparatus and method of manufacturing a semiconductor device

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claim for O.G.	
ISSUE FEE		Primary Examiner	DRAWING		
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner		
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